L Number	Hits	Search Text	DB	Time stamp
-	3634	438/106.ccls. or 438/108.ccls. or 438/119.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:50
-	83473	bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 13:28
-	1384	(438/106.ccls. or 438/108.ccls. or 438/119.ccls.) and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 13:29
-	3285861	temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 13:29
-	926	((438/106.ccls. or 438/108.ccls. or 438/119.ccls.) and bump) and temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 13:30
-	724029	bond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 13:30
-	1329945	bond$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 13:31
-	63592	chip adj2 chip or flip$4 adj2 chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 17:46
-	723	(((438/106.ccls. or 438/108.ccls. or 438/119.ccls.) and bump) and temperature) and bond$4 and (chip adj2 chip or flip$4 adj2 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 17:34
-	304155	flux$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:55
-	4536311	bond$4 or mount$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 17:43
-	102769	misalign$5 or mis adj2 align$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 17:36
-	262642	melting adj2 point	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 11:00
-	5625005	(bond$4 or mount$4) or assembl$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:54

-	71483	temperature near5 (melting adj2 point)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 17:42
-	9969	(temperature near5 (melting adj2 point)) same (chip or die or substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 17:42
-	6252	(bond$4 or mount$4) and ((temperature near5 (melting adj2 point)) same (chip or die or substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 17:45
-	17553	bump near5 (bond$4 or mount$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 17:45
-	411	((bond$4 or mount$4) and ((temperature near5 (melting adj2 point)) same (chip or die or substrate or wafer))) and (bump near5 (bond$4 or mount$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 17:45
-	314	(((bond$4 or mount$4) and ((temperature near5 (melting adj2 point)) same (chip or die or substrate or wafer))) and (bump near5 (bond$4 or mount$4))) and (chip adj2 chip or flip$4 adj2 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 17:46
-	18300	temporar$4 near4 fix$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:52
-	589481	(bump or chip or substrate) adj6 (bump or chip or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:53
-	527	(temporar$4 near4 fix$4) same ((bump or chip or substrate) adj6 (bump or chip or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:53
-	5627850	(bond$4 or mount$4) or assembl$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:54
-	424	((temporar$4 near4 fix$4) same ((bump or chip or substrate) adj6 (bump or chip or substrate))) and ((bond$4 or mount$4) or assembl$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:54
-	13336	flux$4 near15 (bump or chip or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:56
-	42	(((temporar$4 near4 fix$4) same ((bump or chip or substrate) adj6 (bump or chip or substrate))) and ((bond$4 or mount$4) or assembl$4)) and (flux$4 near15 (bump or chip or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:56
-	263226	melting adj3 point	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 11:01

| - | 16 | ((((temporar$4 near4 fix$4) same ((bump or chip or substrate) adj6 (bump or chip or substrate))) and ((bond$4 or mount$4) or assembl$4)) and (flux$4 near15 (bump or chip or substrate))) and (melting adj3 point) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/12 11:01 |